



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20151109001
Datasheet for TMP100/TMP101
Information Only**

Date: 2/8/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP100NA/250	null
TMP100NA/3KG4	null
TMP101NA/250	null
TMP100NA/250G4	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151109001	PCN Date:	2/8/2016
Title:	Datasheet for TMP100/TMP101		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



TMP100, TMP101

SBOS231I–JANUARY 2002–REVISED NOVEMBER 2015

Changes from Revision H (March 2015) to Revision I Page

- Changed body size values in *Device Information* table **1**

Changes from Revision G (November 2007) to Revision H Page

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. **1**
- Changed specification values in *Timing Requirements* table **6**

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP100/TMP101	SBOS231G SBOS231H	SBOS231H SBOS231I

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP100>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP100NA/250	TMP100NA/250G4	TMP100NA/3K	TMP100NA/3KG4
TMP101NA/250	TMP101NA/250G4	TMP101NA/3K	TMP101NA/3KG4

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com